

SOT949-6

HVQFN56, thermal enhanced very thin quad flat package, no leads; 56 terminals, 0.4 mm pitch, 7 mm x 7 mm x 0.85 mm body

10 April 2019

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN56
Package type industry code	HVQFN56
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	01-03-2019
Manufacturer package code	98ASA01369D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	7	-	mm
package width	-	7	-	mm
package height	-	0.85	-	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	56	-	



2 Package outline

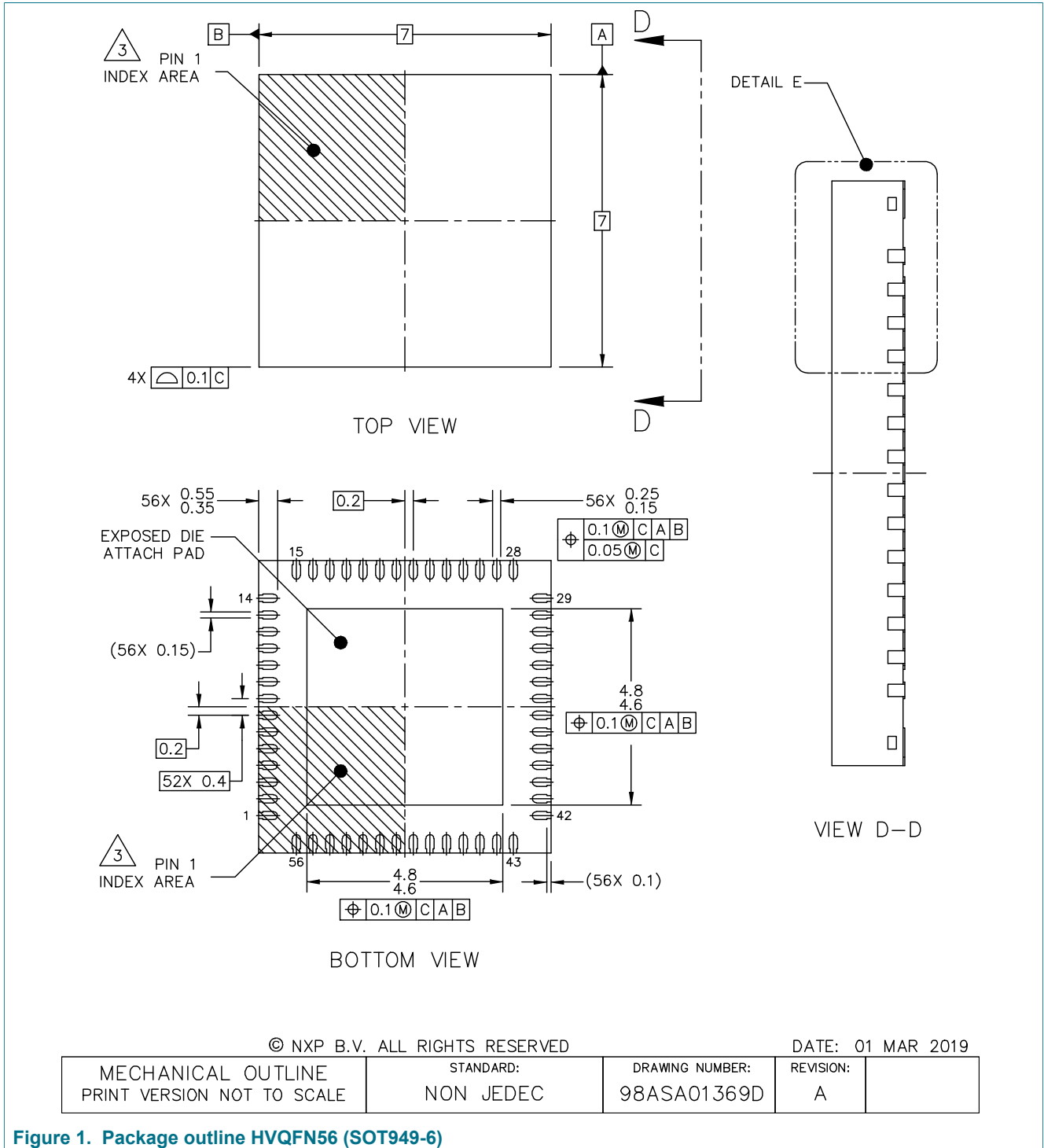


Figure 1. Package outline HVQFN56 (SOT949-6)

HVQFN56, thermal enhanced very thin quad flat package, no leads; 56 terminals, 0.4 mm pitch, 7 mm x 7 mm x 0.85 mm body

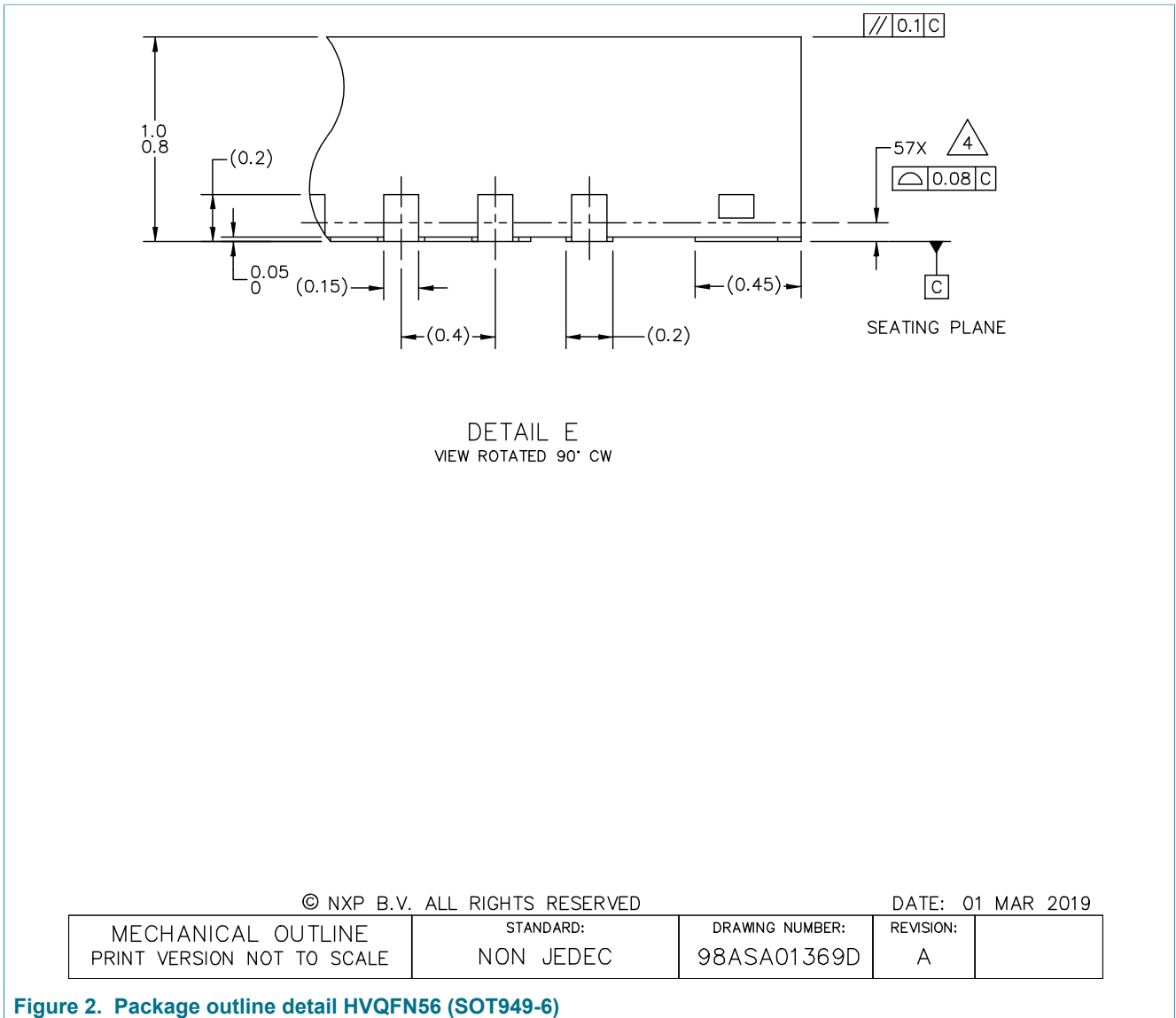


Figure 2. Package outline detail HVQFN56 (SOT949-6)

3 Soldering

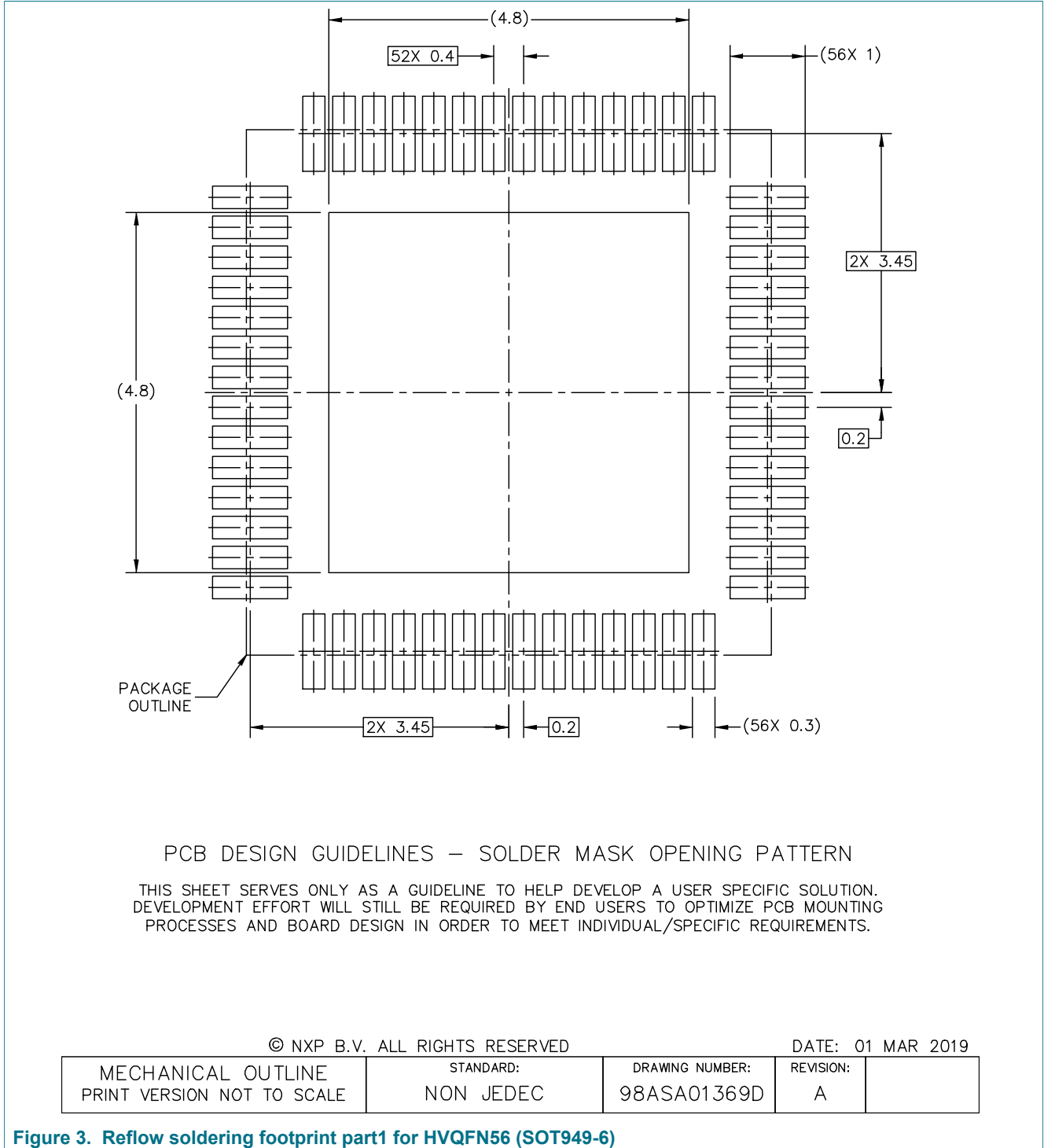
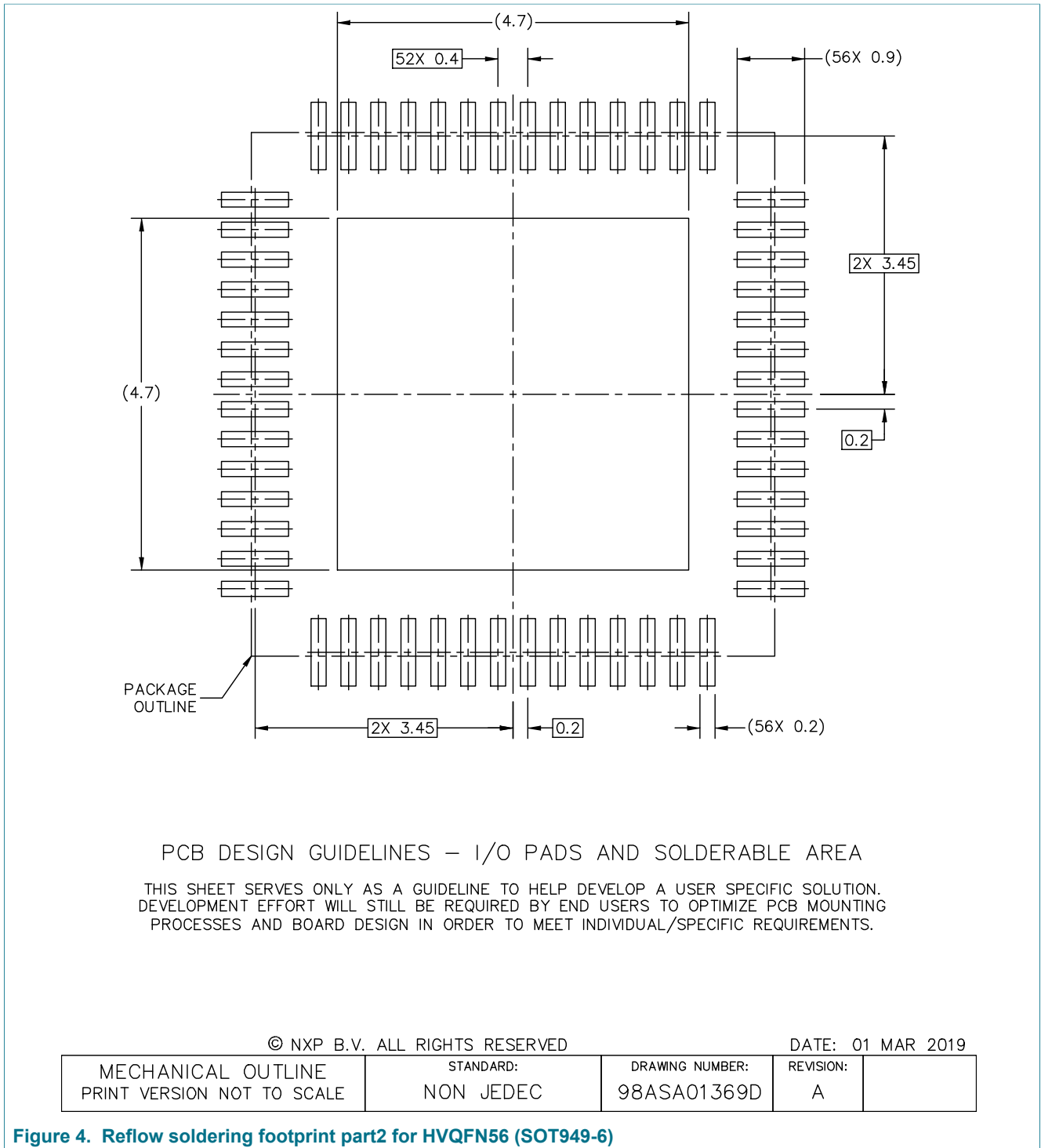


Figure 3. Reflow soldering footprint part1 for HVQFN56 (SOT949-6)

HVQFN56, thermal enhanced very thin quad flat package, no leads; 56 terminals, 0.4 mm pitch, 7 mm x 7 mm x 0.85 mm body



HVQFN56, thermal enhanced very thin quad flat package, no leads; 56 terminals, 0.4 mm pitch, 7 mm x 7 mm x 0.85 mm body

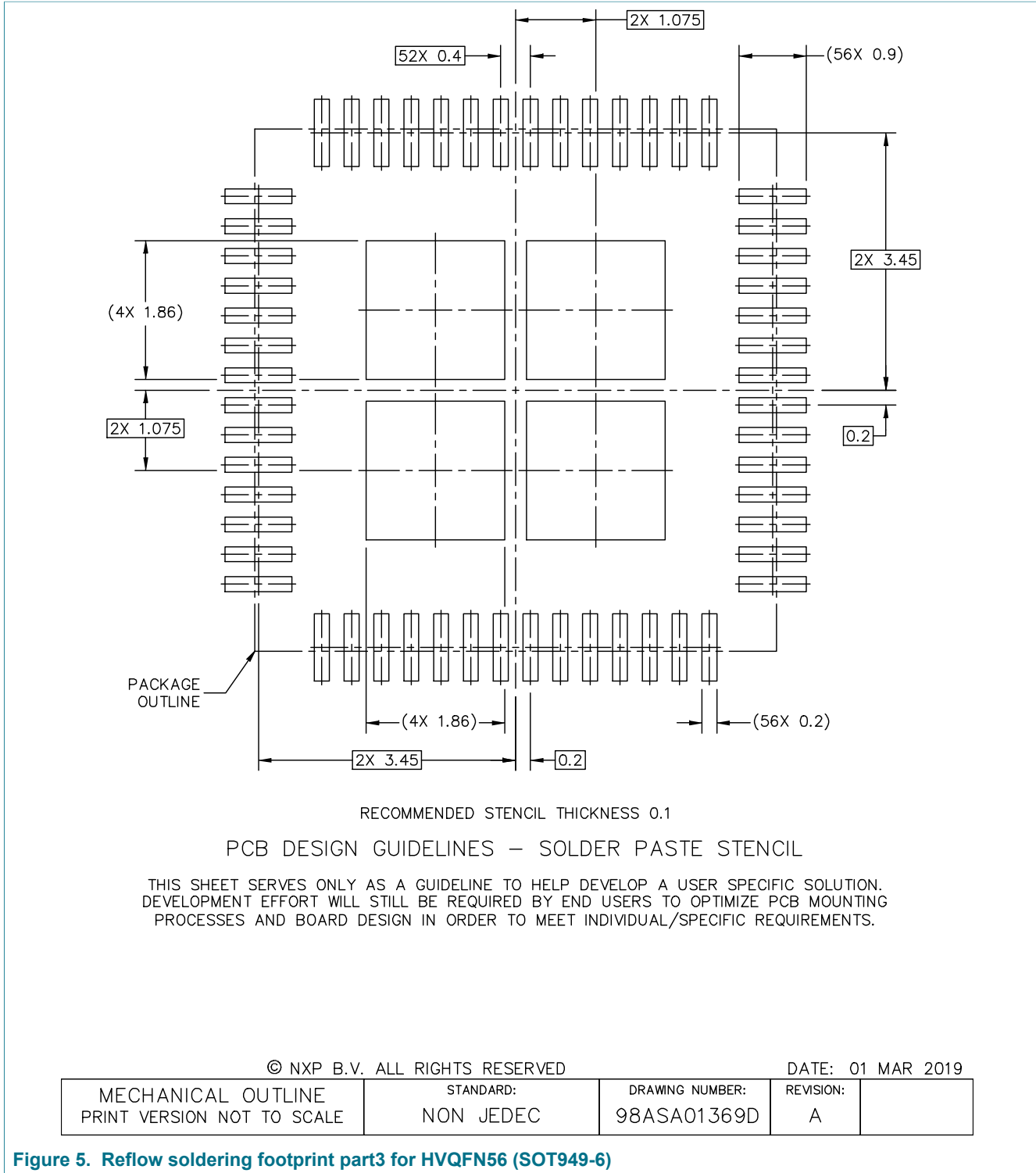


Figure 5. Reflow soldering footprint part3 for HVQFN56 (SOT949-6)

HVQFN56, thermal enhanced very thin quad flat package, no leads; 56 terminals, 0.4 mm pitch, 7 mm x 7 mm x 0.85 mm body

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.15 MM.

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DATE: 01 MAR 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01369D	REVISION: A	
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Figure 6. Package outline note HVQFN56(SOT949-6)

4 Legal information

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